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TO: EXAMINER Maurina T. Rachuba
ART UNIT 3723
EXAMINER'S FAX NUMBER (703) 872-9303

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GROUP 3700

RE: SERIAL NO. 08/824,633
DOCKET NO. PHA 51265B

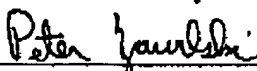
6 Pages (including cover sheet)

This transmission includes:

Response to Final Office Action dated 23-JAN-2003 (5 pgs.)

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Peter Zawilski

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IN THE UNITED STATES PATENT TRADEMARK OFFICE

#32 / Response
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In re the Application of:
Charles Franklin Drill *et al.*

Serial No. 08/824,633

Filed: March 27, 1997

For: A Customized Polishing Pad for Selective Process
Performance During Chemical Mechanical Polishing

Group: 3723

Examiner: Maurina Rachuba.

Docket No.: PHA 51265B

RESPONSE TO JANUARY 23, 2003 OFFICE ACTION

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

In response to the Office Action dated January 23, 2003, please consider the following amendments and remarks.

Remarks

Applicants respectfully request reconsideration of Examiner's position in the final office action of January 23, 2003, in light of the discussion presented below. Claims 22 – 35 are pending and claims 22 – 35 remain rejected. Applicants appreciate Examiner's withdrawal of §102(b) rejections with respect to Neff.

About the Invention

To reiterate, the present invention relates generally to the field of chemical mechanical polishing, and more particularly to polishing pads that have two or more polishing regions with each polishing region having distinct polishing characteristics which are different from those of the other polishing region(s). These polishing regions, which have different, and distinct, polishing characteristics, are arranged such that a workpiece to be polished, e.g., a wafer, can be selectively frictionally engaged with a particular one of those regions. For example, consistent with the present invention, the

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